| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|--|---|---------------------|---------|------------------|
| L1 | 1607 | 257/734.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:18 |
| L2 | 880 | 257/675.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:26 |
| L3 | 1631 | 257/706.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:29 |
| L4 | 833 | 257/720.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:33 |
| L5 | 0 | ((semiconductor adj device) and (circuit adj board) and (heat adj spreader) and (low adj expansion adj material) and (SiC adj particles) and (mean adj grain adj size)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:35 |
| S1 | 1 | ((heat adj (sink or spreader)) with ((low adj expansion) with material)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL) | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 11:38 |
| S2 | 7 | ("5025347" "5844310" "5981085" "6129993" "6132676" "6381094" "6597574").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/08/19 19:29 |
| S3 | 4 | ((heat adj (sink or spreader)) with ((low adj expansion) with material)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/19 19:41 |
| S4 | 3533 | ((heat adj (sink or spreader)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 15:45 |
| S5 | 2 | "6753093" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 15:30 |

| S6 | 7 | ("5025347" "5844310" "5981085" "6129993" "6132676" "6381094" "6597574").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/15 15:30 |
|-----|-----|---|---|----|----|------------------|
| S7 | 319 | S4 and ((heat adj (sink or spreader)) with (((silicon adj carb\$3) or SiC) and (aluminum or AL))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 15:46 |
| S8 | 95 | S7 and (circuit adj board) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:32 |
| S9 | 25 | S8 and (stress with (reduc\$4 or relie\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:12 |
| S10 | 2 | ("6318 44 2").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:34 |
| S11 | 7 | S8 and (auto or automobile) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:38 |
| S12 | 872 | S4 and (circuit adj board) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:39 |
| S13 | 420 | S12 and ((circuit adj board) with heat) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:39 |
| S14 | 292 | S13 and (heat with (chip or semiconductor)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 16:40 |
| S15 | 172 | S14 and stress | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:19 |

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| S16 | 16 | S15 and tobita.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:18 |
| S17 | 0 | S16 and (low adj expansion) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:19 |
| S18 | 0 | S16 and (low with expansion) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:19 |
| S19 | 93 | S14 and (low with expansion) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:19 |
| S20 | 74 | S19 and stress | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 17:19 |
| S21 | 19 | ("5006417").URPN. | USPAT | OR | ON | 2005/09/15 17:24 |
| S22 | 28 | ((heat adj (sink or spreader)) with ((low with expansion) with material)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL) | USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 11:39 |
| S23 | 61 | ((heat adj (sink or spreader)) with ((low with expansion) with material)) and ((heat adj (sink or spreader)) with (between and (chip or (semiconductor adj element)))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 11:43 |
| S24 | 31 | S23 and solder | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 11:43 |
| S25 | 23 | S24 and (metal with substrate) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 21:21 |
| S26 | 1415 | 257/734.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:18 |

| C27 | 010 | 257/575 | 1.0.0.00 | T | T | |
|-----|------|---|---|----|----|------------------|
| S27 | 819 | 257/675.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:26 |
| S28 | 1376 | 257/706.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/12/08 19:28 |
| S29 | 1025 | 257/717.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/16 21:27 |
| S30 | 121 | (low with expansion) and ((SiC or (silicon adj carbide)) with (grain and size)) and (Al or aluminum) and heat | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/10 17:14 |
| S31 | 21 | S30 and (heat adj (spreader or sink)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/24 11:04 |
| S32 | 1 | S31 and (different with grain with size) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/24 11:05 |
| S33 | 19 | S31 and (grain with size) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/24 11:05 |
| S34 | 12 | S33 and heat.ab. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/24 11:05 |
| S35 | 12 | S34 and ((SiC or (silicon adj carbide)) with (Al or aluminum)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/24 11:10 |

| S36 | 38 | ("20020023733" "3574580" | US-PGPUB; | OR | ON | 2006/02/24 11:12 |
|-----|----|--|-----------|----|----|---------------------------------------|
| | | "3678995" "3828848" "3872496" | USPAT; | | | ===================================== |
| | | "3912500" "3913280" "3949263" | USOCR | | | |
| | | "4231195" "4576224" "4649992" | | | | |
| | | "4948388" "5070936" "5096465" | | | | |
| | | "5120495" "5130771" "5382314" | 1 | | | |
| | | "5614320" "5642779" "5696665" | | | | |
| | | "5719441" "5783316" "5786075" | | | | |
| | | "5812570" "5895972" "6031285" | | | | |
| | | "6167948" "6238454" "6264882" | | | | |
| | | "6335863" "6337513" "6361857" | | | | |
| | | "6390181" "6448642" "6517221" | | | | |
| | | "6534792" "6538892").PN. | | | | |
| S37 | 6 | "6507105" | USPAT; | OR | ON | 2006/02/24 11:19 |
| | | | EPO; JPO; | | | |
| | | | DERWENT; | | | |
| | | | IBM_TDB | | | |
| S38 | 17 | (low with expansion) and ((SiC or | US-PGPUB; | OR | ON | 2006/06/10 17:15 |
| | | (silicon adj carbide)) with (grain and | USPAT; | | | |
| j | | size)) and (Al or aluminum) and heat | EPO; JPO; | | | |
| | | and (mean with grain with size) | DERWENT; | | | |
| | | , <u>5</u> | IBM_TDB | | | |